

## Features

- Split Gate Trench MOSFET technology
- Excellent package for heat dissipation
- High density cell design for low  $R_{DS(ON)}$

## Applications

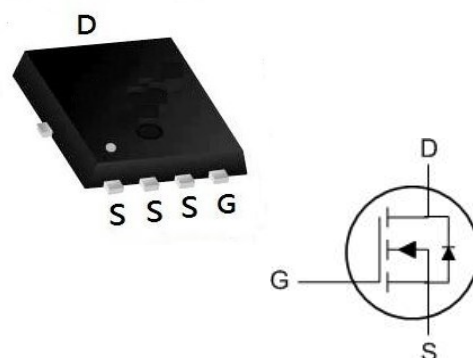
- DC-DC Converters
- Power management functions
- Synchronous-rectification applications

## Product Summary



| BVDSS | RDSON | ID   |
|-------|-------|------|
| 60V   | 1.1mΩ | 200A |

## PDFN5060-8L Pin Configuration



## Absolute Maximum Ratings

| Symbol                      | Parameter                                      | Rating     | Units            |
|-----------------------------|------------------------------------------------|------------|------------------|
| $V_{DS}$                    | Drain-Source Voltage                           | 60         | V                |
| $V_{GS}$                    | Gate-Source Voltage                            | $\pm 20$   | V                |
| $I_D@T_C=25^\circ\text{C}$  | Continuous Drain Current, $V_{GS} @ 10V^{1,6}$ | 200        | A                |
| $I_D@T_C=100^\circ\text{C}$ | Continuous Drain Current, $V_{GS} @ 10V^{1,6}$ | 157        | A                |
| $I_{DM}$                    | Pulsed Drain Current <sup>2</sup>              | 1000       | A                |
| EAS                         | Single Pulse Avalanche Energy <sup>3</sup>     | 961        | mJ               |
| $I_{AS}$                    | Avalanche Current                              | ---        | A                |
| $P_D@T_C=25^\circ\text{C}$  | Total Power Dissipation <sup>4</sup>           | 139        | W                |
| $T_{STG}$                   | Storage Temperature Range                      | -55 to 150 | $^\circ\text{C}$ |
| $T_J$                       | Operating Junction Temperature Range           | -55 to 150 | $^\circ\text{C}$ |

## Thermal Data

| Symbol          | Parameter                                        | Typ. | Max. | Unit               |
|-----------------|--------------------------------------------------|------|------|--------------------|
| $R_{\theta JA}$ | Thermal Resistance Junction-Ambient <sup>1</sup> | ---  | 56   | $^\circ\text{C/W}$ |
| $R_{\theta JC}$ | Thermal Resistance Junction-Case <sup>1</sup>    | ---  | 0.9  | $^\circ\text{C/W}$ |

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

| Symbol                       | Parameter                                      | Conditions                                                 | Min. | Typ. | Max.      | Unit                       |
|------------------------------|------------------------------------------------|------------------------------------------------------------|------|------|-----------|----------------------------|
| $BV_{DSS}$                   | Drain-Source Breakdown Voltage                 | $V_{GS}=0V$ , $I_D=250\mu A$                               | 60   | ---  | ---       | V                          |
| $\Delta BV_{DSS}/\Delta T_J$ | $BV_{DSS}$ Temperature Coefficient             | Reference to $25^\circ\text{C}$ , $I_D=1\text{mA}$         | ---  | ---  | ---       | $V/^\circ\text{C}$         |
| $R_{DS(ON)}$                 | Static Drain-Source On-Resistance <sup>2</sup> | $V_{GS}=10V$ , $I_D=1A$                                    | ---  | 1.1  | 1.4       | m $\Omega$                 |
|                              |                                                | $V_{GS}=4.5V$ , $I_D=1A$                                   | ---  | ---  | ---       |                            |
| $V_{GS(th)}$                 | Gate Threshold Voltage                         | $V_{GS}=V_{DS}$ , $I_D=250\mu A$                           | 2.2  | 2.4  | 3.8       | V                          |
| $\Delta V_{GS(th)}$          | $V_{GS(th)}$ Temperature Coefficient           |                                                            | ---  | ---  | ---       | $\text{mV}/^\circ\text{C}$ |
| $I_{DSS}$                    | Drain-Source Leakage Current                   | $V_{DS}=60V$ , $V_{GS}=0V$ , $T_J=25^\circ\text{C}$        | ---  | ---  | 1         | $\mu A$                    |
|                              |                                                | $V_{DS}=60V$ , $V_{GS}=0V$ , $T_J=100^\circ\text{C}$       | ---  | ---  | 100       |                            |
| $I_{GSS}$                    | Gate-Source Leakage Current                    | $V_{GS}=\pm 20V$ , $V_{DS}=0V$                             | ---  | ---  | $\pm 100$ | nA                         |
| $g_{fs}$                     | Forward Transconductance                       | $V_{DS}=10V$ , $I_D=14A$                                   | ---  | 209  | ---       | S                          |
| $R_g$                        | Gate Resistance                                | $V_{DS}=0V$ , $V_{GS}=0V$ , $f=1\text{MHz}$                | ---  | 1.7  | ---       | $\Omega$                   |
| $Q_g$                        | Total Gate Charge                              | $V_{DS}=30V$ , $V_{GS}=10V$ , $I_D=50A$                    | ---  | 103  | ---       | nC                         |
| $Q_{gs}$                     | Gate-Source Charge                             |                                                            | ---  | 38   | ---       |                            |
| $Q_{gd}$                     | Gate-Drain Charge                              |                                                            | ---  | 13   | ---       |                            |
| $T_{d(on)}$                  | Turn-On Delay Time                             | $V_{GS}=10V$ , $V_{DD}=30V$ ,<br>$R_G=3\Omega$ , $I_D=50A$ | ---  | 24.2 | ---       | ns                         |
| $T_r$                        | Rise Time                                      |                                                            | ---  | 58.2 | ---       |                            |
| $T_{d(off)}$                 | Turn-Off Delay Time                            |                                                            | ---  | 62.5 | ---       |                            |
| $T_f$                        | Fall Time                                      |                                                            | ---  | 26.4 | ---       |                            |
| $C_{iss}$                    | Input Capacitance                              | $V_{DS}=30V$ , $V_{GS}=0V$ , $f=1\text{MHz}$               | ---  | 7156 | ---       | pF                         |
| $C_{oss}$                    | Output Capacitance                             |                                                            | ---  | 2380 | ---       |                            |
| $C_{rss}$                    | Reverse Transfer Capacitance                   |                                                            | ---  | 69   | ---       |                            |

**Diode Characteristics**

| Symbol   | Parameter                                | Conditions                                                | Min. | Typ.  | Max. | Unit |
|----------|------------------------------------------|-----------------------------------------------------------|------|-------|------|------|
| $I_S$    | Continuous Source Current <sup>1,4</sup> | $V_G=V_D=0V$ , Force Current                              | ---  | ---   | 200  | A    |
| $V_{SD}$ | Diode Forward Voltage <sup>2</sup>       | $V_{GS}=0V$ , $I_S=7A$ , $T_J=25^\circ\text{C}$           | ---  | ---   | 1.2  | V    |
| $t_{rr}$ | Reverse Recovery Time                    | $I_F=7A$ , $di/dt=100A/\mu s$ ,<br>$T_J=25^\circ\text{C}$ | ---  | 73.4  | ---  | nS   |
| $Q_{rr}$ | Reverse Recovery Charge                  |                                                           | ---  | 107.9 | ---  | nC   |

Notes:

1. Repetitive rating, pulse width limited by junction temperature  $T_{J(MAX)}=150^\circ\text{C}$ .
2. The test condition is  $V_{DD}=45V$ ,  $V_{GS}=10V$ ,  $L=0.4\text{mH}$ .
3. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.
4. The data tested by pulsed, pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
5. This value is guaranteed by design hence it is not included in the production test.

## Typical Performance Characteristics

Fig 1: Output Characteristics

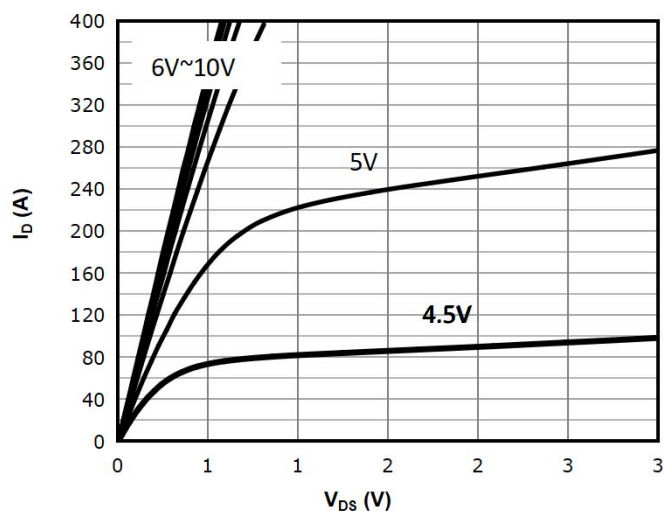


Fig 2: Transfer Characteristics

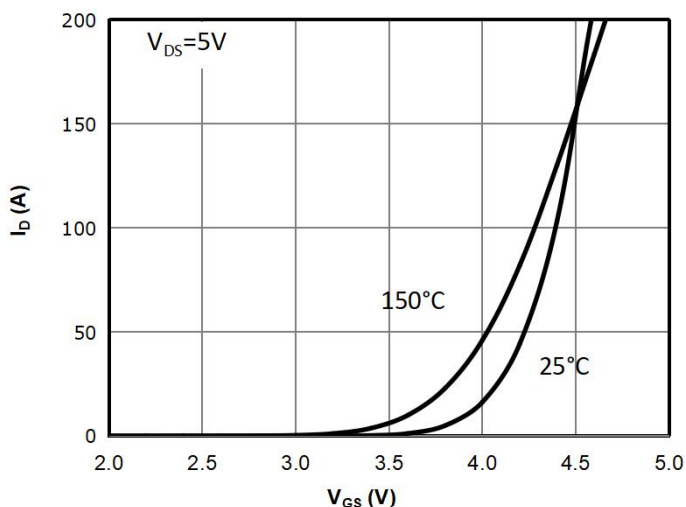


Fig 3:  $R_{DS(on)}$  vs Drain Current and Gate Voltage

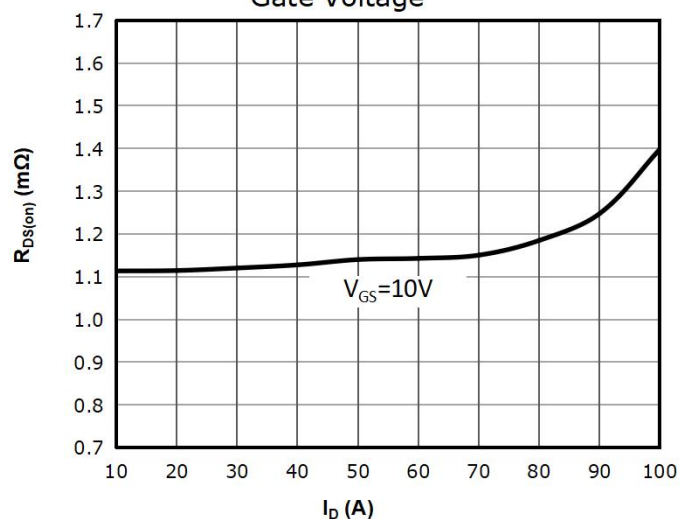


Fig 4:  $R_{DS(on)}$  vs Gate Voltage

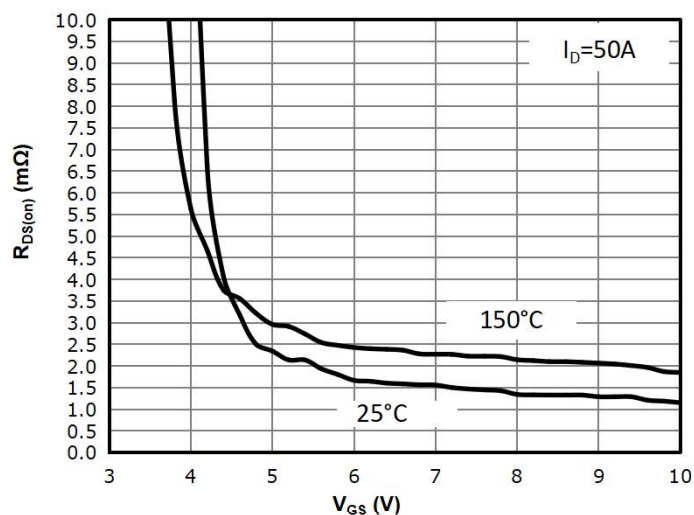


Fig 5:  $R_{DS(on)}$  vs. Temperature

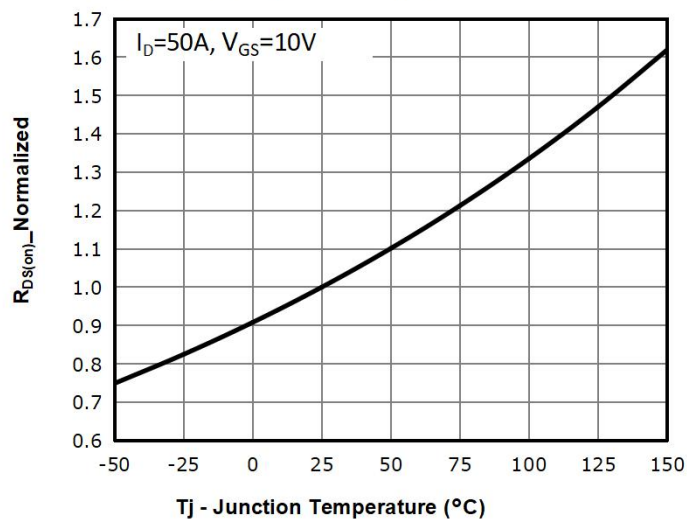


Fig 6:  $V_{GS(th)}$  vs. Temperature

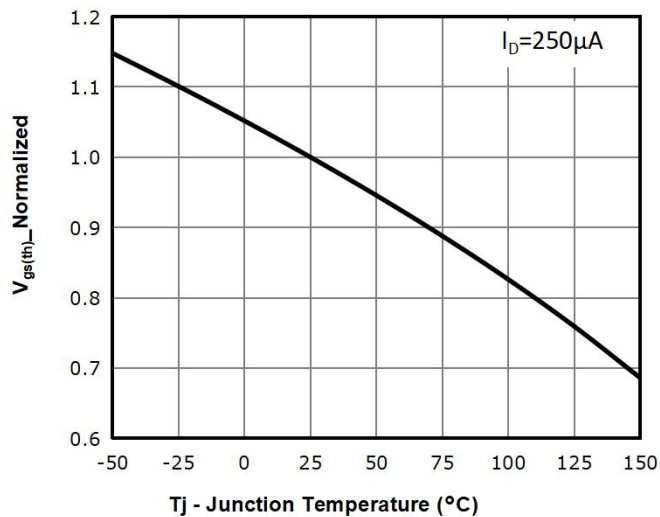


Fig 7: BVdss vs. Temperature

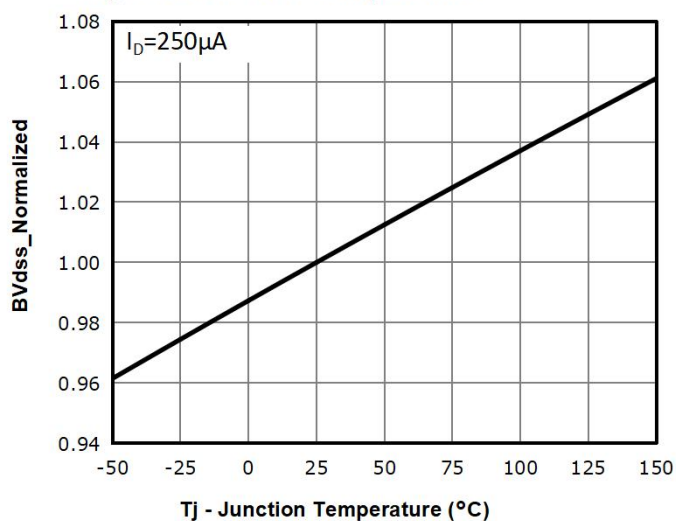


Fig 8: Capacitance Characteristics

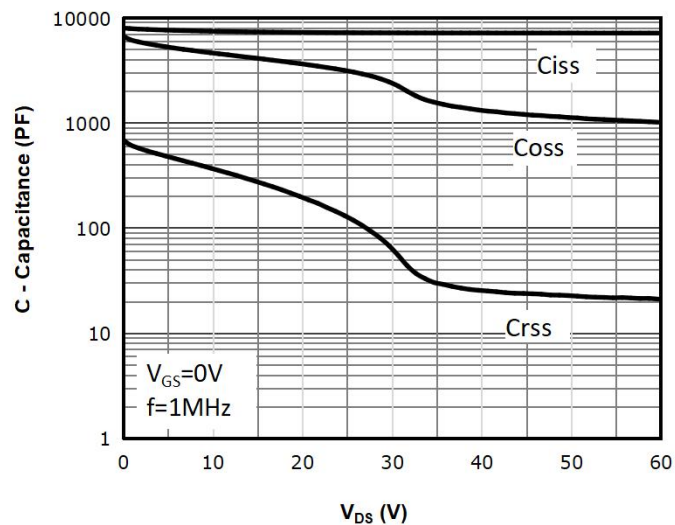


Fig 9: Gate Charge Characteristics

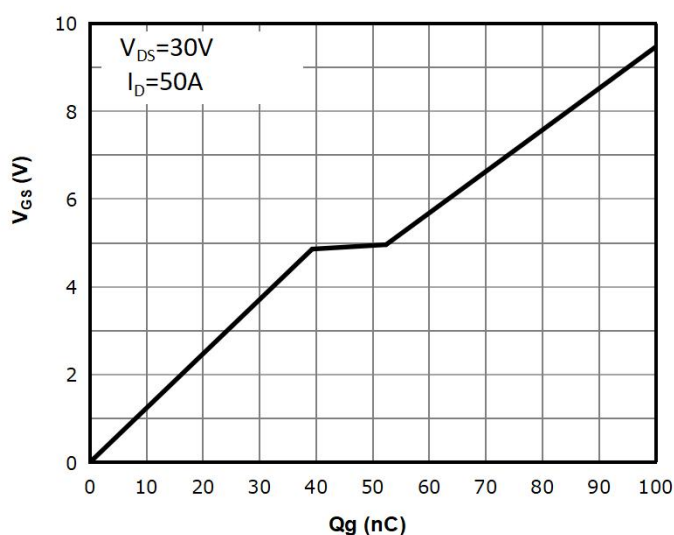


Fig 10: Body-diode Forward Characteristics

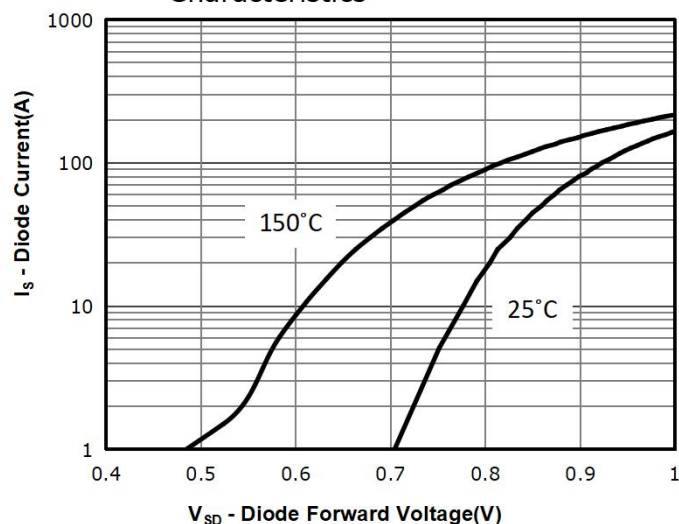


Fig 11: Power Dissipation

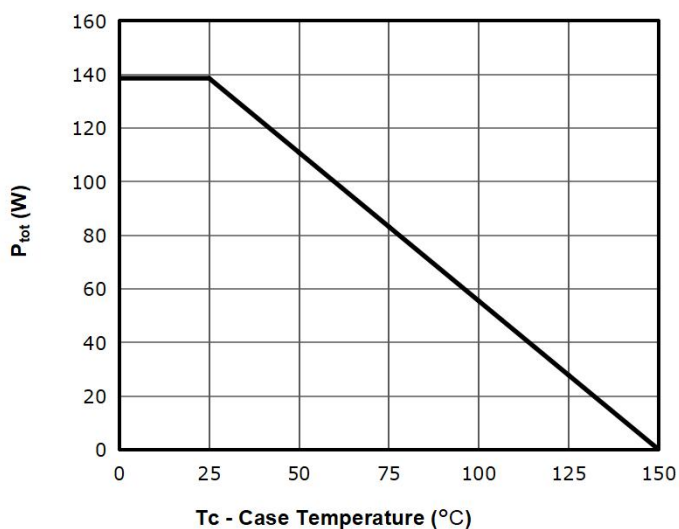


Fig 12: Drain Current Derating

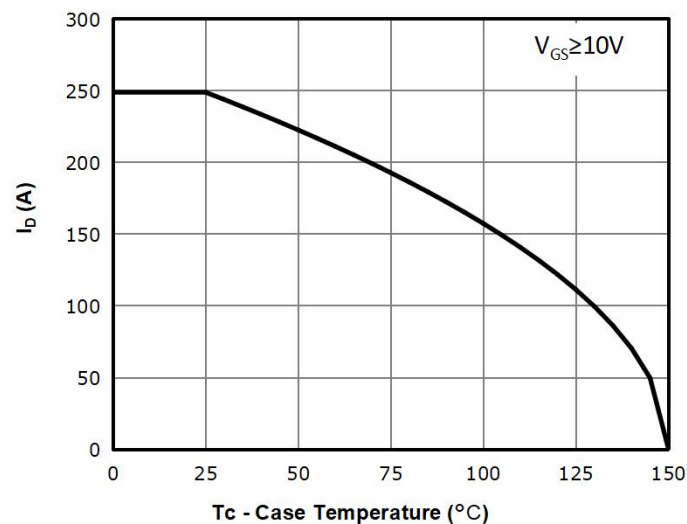


Fig 13: Safe Operating Area

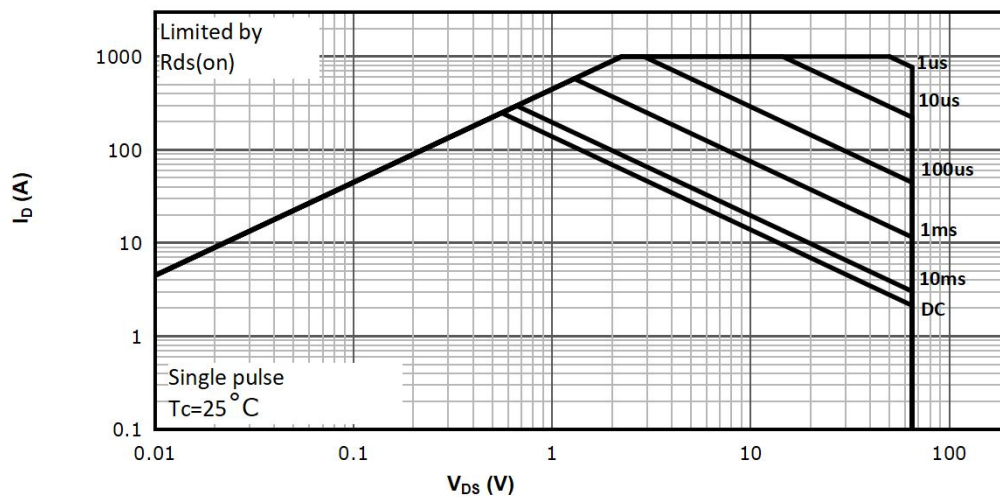
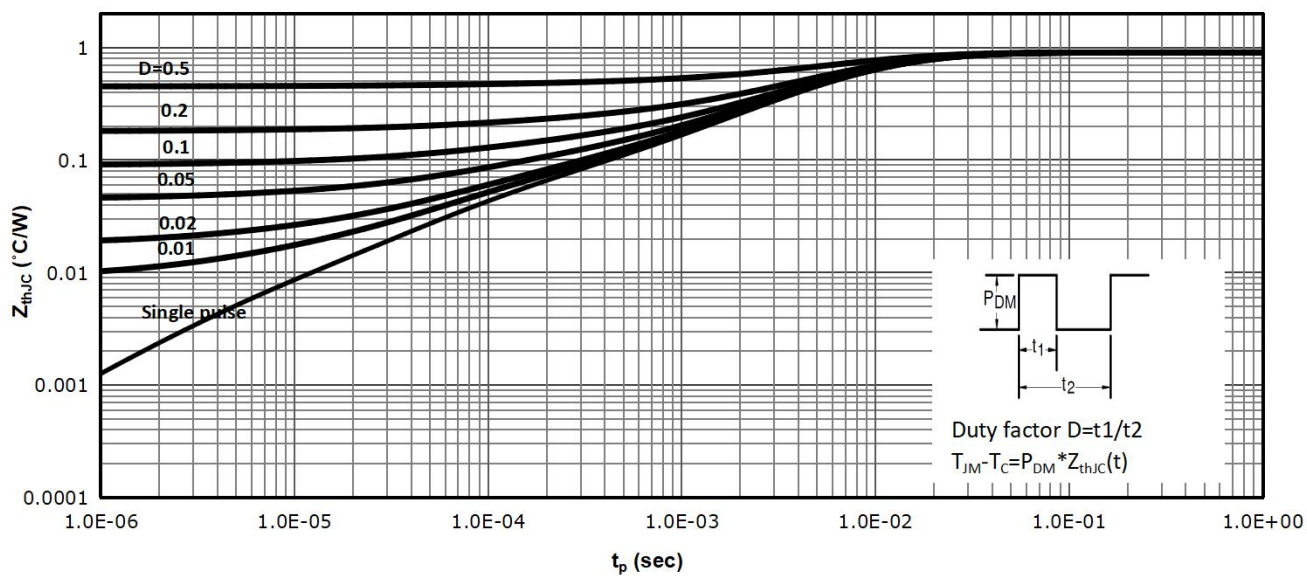
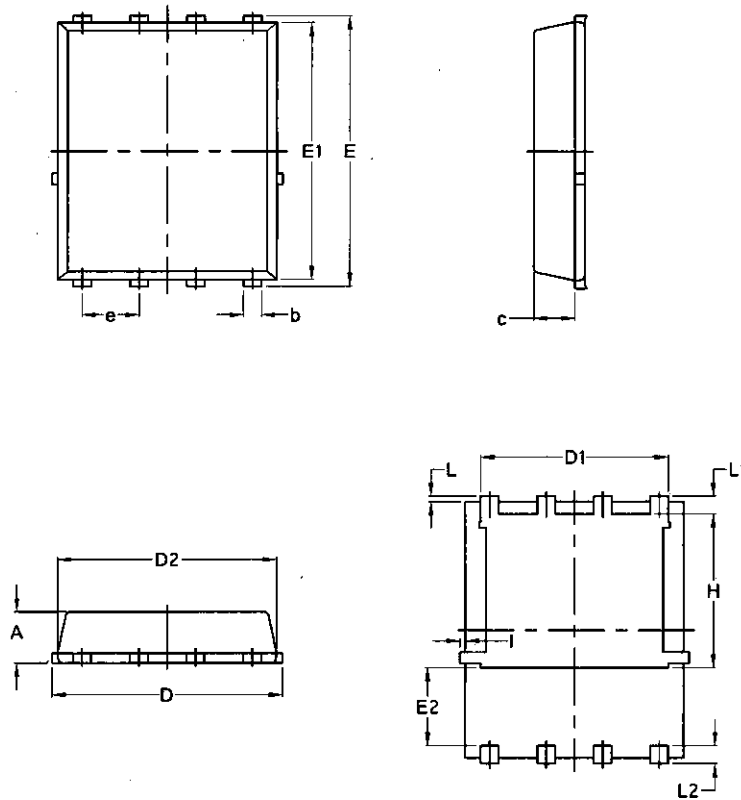


Fig 14: Max. Transient Thermal Impedance



**Package Mechanical Data-PDFN5060-8L- Single**


| Symbol | Common   |        |          |        |
|--------|----------|--------|----------|--------|
|        | mm       |        | Inch     |        |
|        | Mim      | Max    | Min      | Max    |
| A      | 1.03     | 1.17   | 0.0406   | 0.0461 |
| b      | 0.34     | 0.48   | 0.0134   | 0.0189 |
| c      | 0.824    | 0.0970 | 0.0324   | 0.082  |
| D      | 4.80     | 5.40   | 0.1890   | 0.2126 |
| D1     | 4.11     | 4.31   | 0.1618   | 0.1697 |
| D2     | 4.80     | 5.00   | 0.1890   | 0.1969 |
| E      | 5.95     | 6.15   | 0.2343   | 0.2421 |
| E1     | 5.65     | 5.85   | 0.2224   | 0.2303 |
| E2     | 1.60     | /      | 0.0630   | /      |
| e      | 1.27 BSC |        | 0.05 BSC |        |
| L      | 0.05     | 0.25   | 0.0020   | 0.0098 |
| L1     | 0.38     | 0.50   | 0.0150   | 0.0197 |
| L2     | 0.38     | 0.50   | 0.0150   | 0.0197 |
| H      | 3.30     | 3.50   | 0.1299   | 0.1378 |
| I      | /        | 0.18   | /        | 0.0070 |